DEVICE SPECIFICATIONS

NI PXIe-5645R

Reconfigurable 6 GHz RF Vector Signal Transceiver with I/Q Interface

This document lists specifications for the NI PXIe-5645R (NI 5645R) RF vector signal transceiver (VST).

In this document, the term *vector signal analyzer* (VSA) refers to the RF input subsystem of the VST, and the term *vector signal generator* (VSG) refers to the RF output subsystem of the VST.

Specifications are warranted by design and under the following conditions, unless otherwise noted:

- 30 minutes warm-up time.
- Calibration cycle is maintained.
- Chassis fan speed is set to High. In addition, NI recommends using slot blockers and EMC filler panels in empty module slots to minimize temperature drift.
- Calibration IP is used properly during the creation of custom FPGA bitfiles.
- Calibration Interconnect cable remains connected between CAL IN and CAL OUT front panel connectors.



Caution Do not disconnect the cable that connects CAL IN to CAL OUT. Removing the cable from or tampering with the CAL IN or CAL OUT front panel connectors voids the product calibration and specifications are no longer warranted.

Unless otherwise noted, specifications assume the NI 5645R is configured in the following default mode of operation:

Reference Clock source: Internal

RF IN reference level: 0 dBm

• RF OUT power level: 0 dBm

LO tuning mode: Fractional

• LO PLL loop bandwidth: Medium

LO step size: 200 kHz

LO frequency: 2.4 GHz

LO source: Internal

• I/Q IN voltage range: 0.5 V_{pk-pk} differential

I/O IN common-mode voltage: 0 V

• I/Q OUT voltage range: 0.5 V_{pk-pk} differential



- I/O OUT common-mode voltage: 0 V
- I/O OUT load impedance: 50Ω
- Digital equalization enabled for both RF and I/Q channels



Note Within the specifications, *self-calibration* °C refers to the recorded device temperature of the last successful self-calibration. You can read the self-calibration temperature from the device using the appropriate software functions.

Specifications describe the warranted, traceable product performance over ambient temperature ranges of 0 °C to 55 °C, unless otherwise noted.

Typical values describe useful product performance beyond specifications that are not covered by warranty and do not include guardbands for measurement uncertainty or drift. Typical values may not be verified on all units shipped from the factory. Unless otherwise noted, typical values cover the expected performance of units over ambient temperature ranges of 23 °C ± 5 °C with a 90% confidence level, based on measurements taken during development or production.

2σ specifications describe the 95th percentile values in which 95% of the cases are met with a 95% confidence for any ambient temperature of 23 °C \pm 5 °C.

Nominal values (or supplemental information) describe additional information about the product that may be useful, including expected performance that is not covered under Specifications or Typical values. Nominal values are not covered by warranty.

Specifications are subject to change without notice. For the most recent device specifications, visit ni.com/manuals.

National Instruments RF devices are capable of producing and/or acquiring accurate signals within common Medical Implantable Communication System (MICS) frequency bands. NI RF devices are tested and verified in manufacturing for many measurements. For more information about RF device applications, visit ni.com/niglobal to contact a National Instruments branch office



Caution The protection provided by this equipment may be impaired if it is used in a manner not described in the documentation.



Caution Do not disconnect the cable that connects CAL IN to CAL OUT. Removing the cable from or tampering with the CAL IN to CAL OUT front panel connectors voids the product calibration and specifications are no longer warranted.

To access NI 5645R documentation, navigate to Start»All Programs»National Instruments» Vector Signal Transceivers.

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Frequency		
The following characteristics are com-	mon to both RF IN and RF OUT ports.	
Frequency range	65 MHz to 6 GHz	
$Bandwidth^1\\$	80 MHz	
Tuning resolution ²	<1 Hz	
LO step size		

Programmable step size, 200 kHz default

4 MHz, 5 MHz, 6 MHz, 12 MHz, 24 MHz

Fractional mode

Integer mode

 $^{^1}$ Digitally equalized RF input and RF output bandwidth. Bandwidth is restricted to 20 MHz for LO frequencies \leq 109 MHz and restricted to 40 MHz for LO frequencies between 109 MHz and 375 MHz.

² Tuning resolution combines LO step size capability and frequency shift DSP implemented on the FPGA.

Frequency Settling Time

Table 1. Maximum Frequency Settling Time

	Maximum Time (ms)		
Settling Time			High Loop Bandwidth
≤1 × 10 ⁻⁶ of final frequency	1.1	0.95	0.38
≤0.1 × 10 ⁻⁶ of final frequency	1.2	1.05	0.4

The default medium loop bandwidth refers to a setting that adjusts PLL to balance tuning speed and phase noise, and it does not necessarily result in loop bandwidth between low and high.

This specification includes only frequency settling and excludes any residual amplitude settling.

Internal Frequency Reference

Initial adjustment accuracy	±200 × 10 ⁻⁹
Temperature stability	$\pm 1 \times 10^{-6}$, maximum
Aging	±1 × 10 ⁻⁶ per year, maximum
Accuracy	Initial adjustment accuracy ± Aging ± Temperature stability

Frequency Reference Input (REF IN)

Refer to the *REF IN* section.

Frequency Reference/Sample Clock Output (REF OUT)

Refer to the *REF OUT* section.

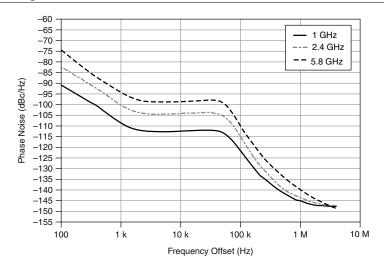
³ Medium loop bandwidth is available only in fractional mode.

Spectral Purity

Table 2. Single Sideband Phase Noise

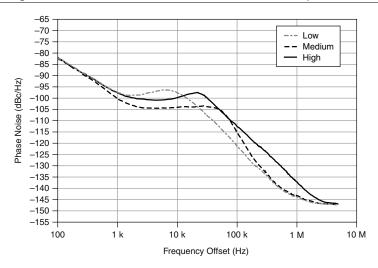
	Phase Noise (dBc/Hz), 20 kHz Offset (Single Sideband)		
Frequency	Low Loop Bandwidth	Medium Loop Bandwidth	High Loop Bandwidth
<3 GHz	-99	-99	-94
3 GHz to 4 GHz	-91	-93	-91
>4 GHz to 6 GHz	-93	-93	-87

Figure 1. Measured Phase Noise⁴ at 1 GHz, 2.4 GHz, and 5.8 GHz



⁴ Conditions: Measured port: LO Out; Reference Clock: internal; medium loop bandwidth.

Figure 2. Measured Phase Noise⁵ at 2.4 GHz Versus Loop Bandwidth



RF Input

Amplitude Range

Amplitude range	Average noise level to +30 dBm (CW RMS)
RF reference level range/resolution	≥60 dB in 1 dB nominal steps

Amplitude Settling Time

<0.1 dB of final value ⁶	125 μs, typical
<0.5 dB of final value ⁷ , with LO retuned	300 μs

⁵ Conditions: Measured port: LO Out; Reference Clock: internal.

⁶ Constant LO frequency, constant RF input signal, varying input reference level.

⁷ LO tuning across harmonic filter bands, constant RF input signal, varying input reference level.

Absolute Amplitude Accuracy

Table 3. VSA Absolute Amplitude Accuracy (dB)

15 °C to 35 °C		0 °C to 55 °C		
Frequency	Self-Calibration °C ± 1 °C	Self-Calibration °C ± 5 °C	Self-Calibration °C ± 1 °C	Self-Calibration °C ± 5 °C
65 MHz to	_	±0.70	_	±0.75
<375 MHz	_	± 0.65 (95th percentile, $\approx 2\sigma$)	_	± 0.65 (95th percentile, $\approx 2\sigma$)
	±0.34, typical	±0.50, typical	±0.36, typical	±0.55, typical
375 MHz to	_	±0.65	_	±0.70
<2 GHz	_	± 0.55 (95th percentile, $\approx 2\sigma$)	_	± 0.55 (95th percentile, $\approx 2\sigma$)
	±0.17, typical	±0.35, typical	±0.22, typical	±0.40, typical
2 GHz to	_	±0.70	_	±0.75
<4 GHz	_	± 0.55 (95th percentile, $\approx 2\sigma$)	_	$\pm 0.60 \text{ (95th percentile, } \approx 2\sigma\text{)}$
	±0.23, typical	±0.40, typical	±0.26, typical	±0.40, typical
4 GHz to 6 GHz	_	±0.90	_	±0.95
	_	± 0.75 (95th percentile, $\approx 2\sigma$)	_	± 0.80 (95th percentile, $\approx 2\sigma$)
	±0.30, typical	±0.55, typical	±0.33, typical	±0.55, typical

Conditions: reference level -30 dBm to +30 dBm; measured at 3.75 MHz offset from the configured center frequency; measurement performed after the NI 5645R has settled.

For reference levels <-30 dBm, absolute amplitude gain accuracy is ± 0.6 dB, typical for frequencies \leq 4 GHz, and \pm 0.8 dB, typical for frequencies > 4 GHz. Performance depends on signal-to-noise ratio.

This specification is valid only when the module is operating within the specified ambient temperature range and within the specified range from the last self-calibration temperature, as measured with the onboard temperature sensors.

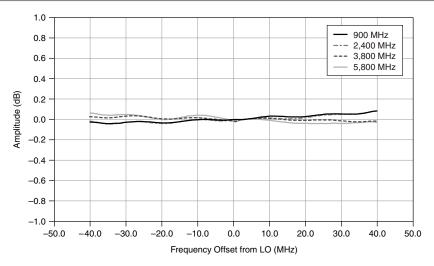
Frequency Response

Table 4. VSA Frequency Response (dB) (Amplitude, Equalized)

RF Input Frequency	Bandwidth	Self-Calibration °C ± 5 °C
≤109 MHz	20 MHz	±1.0, typical
>109 MHz to 375 MHz	20 MHz	±0.5
	40 MHz	±1.0, typical
>375 MHz to 6 GHz	80 MHz	±0.5

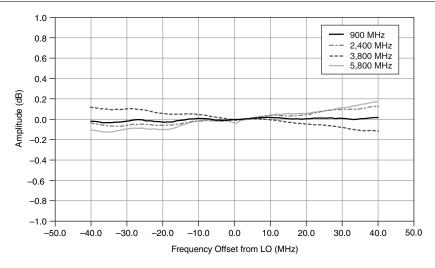
Conditions: Reference level -30 dBm to +30 dBm. This specification is valid only when the module is operating within the specified ambient temperature range and within the specified range from the last self-calibration temperature, as measured with the onboard temperature sensors.

Figure 3. Measured Frequency Response, 8 0 dBm Reference Level, Equalized



⁸ Measurement performed after self-calibration.

Figure 4. Measured Frequency Response, 8 - 30 dBm Reference Level, Equalized



Average Noise Density

Table 5. Average Noise Density (dBm/Hz)

Conton Engagement	Average Noise Level		
Center Frequency	-50 dBm Reference Level	-10 dBm Reference Level	
65 MHz to 4 GHz	-159	-145	
	-161, typical	-148, typical	
>4 GHz to 6 GHz	-156	-144	
	-158, typical	-146, typical	

Conditions: input terminated with a 50 Ω load; 50 averages; RMS average noise level normalized to a 1 Hz noise bandwidth.

The -50 dBm reference level configuration has the inline preamplifier enabled, which represents the high sensitivity operation of the receive path.

Spurious Responses

Nonharmonic Spurs

Table 6. Nonharmonic Spurs (dBc)

Frequency	<100 kHz Offset	≥100 kHz Offset	>1 MHz Offset
65 MHz to 3 GHz	<-55, typical	<-60	<-75
>3 GHz to 6 GHz	<-55, typical	<-55	<-70

Conditions: reference level ≥-30 dBm. Measured with a single tone, -1 dBr, where dBr is referenced to the configured RF reference level.

LO Residual Power

Table 7. VSA LO Residual Power (dBr⁹)

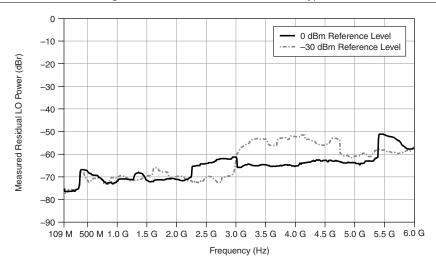
Center Frequency	Self-Calibration °C ± 1 °C Self-Calibration °C ± 5 °C		
- Content Frequency	och cambration of the	Cen Cambration C 2 C C	
≤109 MHz	_	-62	
	-70, typical	-67, typical	
>109 MHz to 2 GHz	_	-58	
	-65, typical	-61, typical	
>2 GHz to 3 GHz	_	-55	
	-60, typical	-58, typical	
>3 GHz to 6 GHz	_	-45	
	-56, typical	-48, typical	

Conditions: Reference levels -30 dBm to +30 dBm; Measured at ADC.

This specification is valid only when the module is operating within the specified ambient temperature range and within the specified range from the last self-calibration temperature, as measured with the onboard temperature sensors.

For optimal performance, NI recommends running self-calibration when the NI 5645R temperature drifts ± 5 °C from the temperature at the last self-calibration. For temperature changes >±5 °C from self-calibration, LO residual power is -35 dBr.

⁹ dBr is relative to the full scale of the configured RF reference level.



Residual Sideband Image

Table 8. VSA Residual Sideband Image, 80 MHz Bandwidth (dBc)

Center Frequency	Self-Calibration °C ± 1 °C	Self-Calibration °C ± 5 °C	
≤109 MHz	_	-40	
	-60, typical	-50, typical	
>109 MHz to 500 MHz	_	-40	
	-50, typical	-45, typical	
>500 MHz to 3 GHz	_	-65	
	-75, typical	-70, typical	
>3 GHz to 5 GHz	_	-55	
	-70, typical	-60, typical	

¹⁰ Conditions: VSA frequency range 109 MHz to 6 GHz. Measurement performed after selfcalibraton.

Table 8. VSA Residual Sideband Image, 80 MHz Bandwidth (dBc) (Continued)

Center Frequency	Self-Calibration °C ± 1 °C	Self-Calibration °C ± 5 °C	
>5 GHz to 6 GHz	_	-60	
	-70, typical	-65, typical	

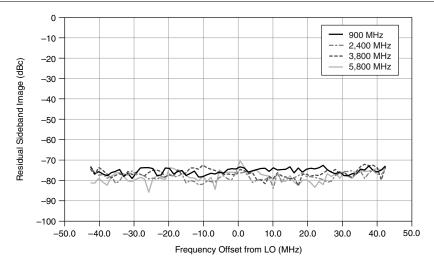
Conditions: Reference levels -30 dBm to +30 dBm.

This specification describes the maximum residual sideband image within an 80 MHz bandwidth at a given RF center frequency. Bandwidth is restricted to 20 MHz for LO frequencies ≤ 109 MHz.

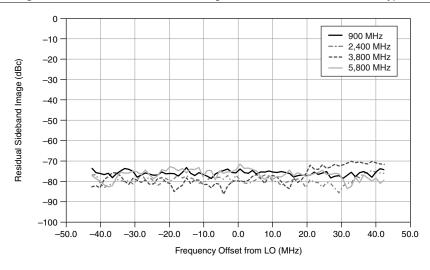
This specification is valid only when the module is operating within the specified ambient temperature range and within the specified range from the last self-calibration temperature, as measured with the onboard temperature sensors.

For optimal performance, NI recommends running self-calibration when the NI 5645R temperature drifts ± 5 °C from the temperature at the last self-calibration. For temperature changes >± 5 °C from self-calibration, residual image suppression is -40 dBc.

Figure 6. VSA Residual Sideband Image, 11 0 dBm Reference Level, Typical



Measurement performed after self-calibration.



Third-Order Input Intermodulation

Table 9. Third-Order Input Intercept Point (IIP3), -5 dBm Reference Level, Typical

Frequency Range	IIP ₃ (dBm)	
65 MHz to 1.5 GHz	19	
>1.5 GHz to 6 GHz	20	

Conditions: two -10 dBm tones, 700 kHz apart at RF IN; reference level: -5 dBm <4 GHz, -2 dBm reference level otherwise; nominal noise floor: -148 dBm/Hz for -5 dBm reference level, -145 dBm/Hz for -2 dBm reference level.

Table 10. Third-Order Input Intercept Point (IIP3), -20 dBm Reference Level, Typical

Frequency Range	IIP ₃ (dBm)
65 MHz to 200 MHz	9
>200 MHz to 2 GHz	11
>2 GHz to 3.75 GHz	8
>3.75 GHz to 4.25 GHz	6
>4.25 GHz to 5 GHz	4

Table 10. Third-Order Input Intercept Point (IIP₃), -20 dBm Reference Level, Typical (Continued)

Frequency Range	IIP ₃ (dBm)	
>5 GHz to 6 GHz	1	

Conditions: two -25 dBm tones, 700 kHz apart at RF IN; reference level: -20 dBm; nominal

noise floor: -157 dBm/Hz.

Second-Order Input Intermodulation

Table 11. Second-Order Input Intercept Point (IIP2), -2 dBm Reference Level, Typical

Frequency Range	IIP ₂ (dBm)	
65 MHz to 1.5 GHz	67	
>1.5 GHz to 4 GHz	58	
>4 GHz to 6 GHz	52	

Conditions: two -10 dBm tones, 700 kHz apart at RF IN; reference level: -2 dBm; nominal noise floor: -145 dBm/Hz.

RF Output

Power Range

Table 12. Power Range

Output Type	Frequency	Power Range		
CW	<4 GHz	Noise floor to +10 dBm, average power ¹²	Noise floor to +15 dBm, average power, nominal	
	≥4 GHz	Noise floor to +7 dBm, average power ¹²	Noise floor to +12 dBm, average power, nominal	

¹² Higher output is uncalibrated and may be compressed.

Table 12. Power Range (Continued)

Output Type	Frequency	Power Range		
Modulated ¹³	<4 GHz	Noise floor to +6 dBm, average power	_	
	≥4 GHz	Noise floor to +3 dBm, average power	_	

Output attenuator resolution	2 dB, nominal
Digital attenuation resolution ¹⁴	0.1 dB or better

Related Information

Refer to the Considering Average Power and Crest Factor topic of the NI RF Vector Signal Transceivers Help for more information about modulated signal power.

Amplitude Settling Time

0.1 dB of final value ¹⁵	50 μs
0.5 dB of final value ¹⁶ , with LO retuned	300 μs

Output Power Level Accuracy

Table 13. Output Power Level Accuracy (dB)

	15 °C to 35 °C		0 °C to 55 °C	
Center Frequency	Self- Calibration °C ± 1 °C	Self-Calibration °C ± 5 °C	Self- Calibration °C ± 1 °C	Self-Calibration °C ± 5 °C
65 MHz to	_	±0.70	_	±0.90
<109 MHz	_	± 0.55 (95th percentile, $\approx 2\sigma$)	_	± 0.65 (95th percentile, $\approx 2\sigma$)
	±0.26, typical	±0.40, typical	±0.36, typical	±0.50, typical

¹³ Up to 12 dB crest factor, based on 3GPP LTE uplink requirements.

¹⁴ Average output power ≥ -100 dBm.

¹⁵ Constant LO frequency, varying RF output power range. Power levels ≤ 0 dBm. 175 μs for power levels > 0 dBm.

¹⁶ LO tuning across harmonic filter bands.

Table 13. Output Power Level Accuracy (dB) (Continued)

	15 °C to 35 °C		0 °C to 55 °C	
Center Frequency	Self- Calibration °C ± 1 °C	Self-Calibration °C ± 5 °C	Self- Calibration °C ± 1 °C	Self-Calibration °C ± 5 °C
109 MHz to		±0.75		±0.90
<270 MHz ¹⁷		± 0.60 (95th percentile; $\approx 2\sigma$)		± 0.70 (95th percentile; $\approx 2\sigma$)
	±0.26, typical	±0.45, typical	±0.36, typical	±0.55, typical
270 MHz to	_	±0.70	_	±0.90
<375 MHz	_	± 0.55 (95th percentile, $\approx 2\sigma$)	_	± 0.65 (95th percentile, $\approx 2\sigma$)
	±0.26, typical	±0.40, typical	±0.36, typical	±0.50, typical
375 MHz to	_	±0.75	_	±0.90
<2 GHz	_	± 0.55 (95th percentile, $\approx 2\sigma$)	_	± 0.65 (95th percentile, $\approx 2\sigma$)
	±0.26, typical	±0.40, typical	±0.36, typical	±0.50, typical
2 GHz to <4 GHz	_	±0.75	_	±0.90
	_	± 0.60 (95th percentile, $\approx 2\sigma$)	_	$\pm 0.70 \text{ (95th percentile, } \approx 2\sigma)$
	±0.26, typical	±0.40, typical	±0.36, typical	±0.50, typical

 $^{^{17}}$ Harmonic suppression is reduced in this frequency range. As a result, offset errors may occur depending on whether you are using a true RMS device, such as a power meter.

Table 13. Output Power Level Accuracy (dB) (Continued)

	15 °C to 35 °C		0 °C to 55 °C	
Center Frequency	Self- Calibration °C ± 1 °C	Self-Calibration °C ± 5 °C	Self- Calibration °C ± 1 °C	Self-Calibration °C ± 5 °C
4 GHz to 6 GHz	_	±1.00	_	±1.15
	_	$\pm 0.80 \text{ (95th percentile, } \approx 2\sigma)$	_	± 0.90 (95th percentile, $\approx 2\sigma$)
	±0.28, typical	±0.40, typical	±0.38, typical	±0.60, typical

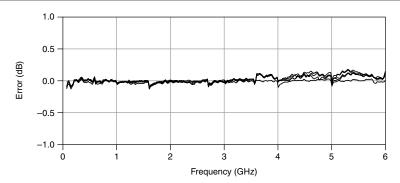
Conditions: CW average power -70 dBm to +10 dBm.

For power <-70 dBm, highly accurate generation can be achieved using digital attenuation, which relies on DAC linearity.

The absolute amplitude accuracy is measured at 3.75 MHz offset from the configured center frequency. The absolute amplitude accuracy measurements are made after the NI 5645R has settled.

This specification is valid only when the module is operating within the specified ambient temperature range and within the specified range from the last self-calibration temperature, as measured with the onboard temperature sensors.

Figure 8. Relative Power Accuracy, -40 dBm to 10 dBm, 10 dB Steps, Typical



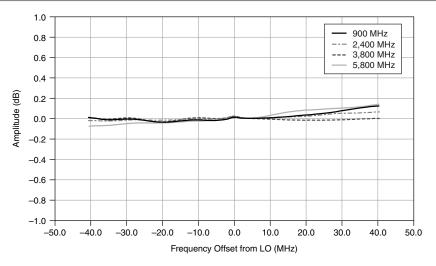
Frequency Response

Table 14. VSG Frequency Response (dB) (Amplitude, Equalized)

Output Frequency	Bandwidth	Self-Calibration °C ± 5 °C
≤109 MHz	20 MHz	±1.0, typical
>109 MHz to 375 MHz	20 MHz	±0.5
	40 MHz	±1.0, typical
>375 MHz to 6 GHz	80 MHz	±0.5

For this specification, frequency refers to the RF output frequency. This specification is valid only when the module is operating within the specified ambient temperature range and within the specified range from the last self-calibration temperature, as measured with the onboard temperature sensors.

Figure 9. VSG Measured Frequency Response¹⁸



Conditions: Output -10 dBm CW tone. Measurement performed after self-calibration.

Output Noise Density

Table 15. Average Output Noise Level (dBm/Hz)

Contar Fraguency	Power Setting			
Center Frequency	-30 dBm	0 dBm	10 dBm	
(5 MII- 42 500 MII-	_	_	-136	
65 MHz to 500 MHz	-168, typical	-150 , typical	-140, typical	
>500 MHz to 2.5 GHz	-168, typical	-150	-141	
>2.5 GHz to 3.5GHz	-168, typical	-149	-139	
>3.5 GHz to 6 GHz	-165, typical	-147	-136	

Conditions: Averages: 200 sweeps; baseband signal attenuation: -40 dB; noise measurement frequency offset: 4 MHz relative to output tone frequency.

Spurious Responses

Harmonics

Table 16. Second Harmonic Level (dBc)

_	
23 °C ± 5 °C	0 °C to 55 °C
-27	-24.8
-29.5, typical	-27.2, typical
-26.3	-24
-28.9, typical	-26.6, typical
-28.9	-26.6
-33.3, typical	-31, typical
	-27 -29.5, typical -26.3 -28.9, typical -28.9

Conditions: Measured using 1 MHz baseband signal -1 dBFS; fundamental signal measured at +6 dBm CW; second harmonic levels nominally <-30 dBc for fundamental output levels of <5 dBm.



Note Higher order harmonic suppression is degraded in the range of 109 MHz to 270 MHz, and third harmonic performance is shown in the following figure. For frequencies outside the range of 109 MHz to 270 MHz, higher order harmonic

distortion is equal to or better than the second harmonic level as specified in the previous table.

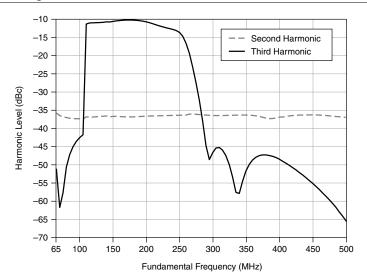


Figure 10. Harmonic Level¹⁹, 65 MHz to 500 MHz, Measured

Nonharmonic Spurs

Table 17. Nonharmonic Spurs (dBc)

		. , ,	
Frequency	<100 kHz Offset	≥100 kHz Offset	>1 MHz Offset
65 MHz to 3 GHz	<-55, typical	<-62	<-75
>3 GHz to 6 GHz	<-55, typical	<-57	<-70
Conditions: output full scale level ≥-30 dBm. Measured with a single tone at -1 dBFS.			

Third-Order Output Intermodulation

Table 18. Third-Order Output Intermodulation Distortion (IMD₃) (dBc), 0 dBm Tones

Fundamental Frequency	Baseband DAC: -2 dBFS	Baseband DAC: -6 dBFS
65 MHz to 1 GHz	-55, typical	-60, typical
>1 GHz to 3 GHz	-56, typical	-53, typical

¹⁹ Measured using 1 MHz baseband signal -1 dBFS; fundamental signal measured at +6 dBm CW.

Table 18. Third-Order Output Intermodulation Distortion (IMD₃) (dBc), 0 dBm Tones (Continued)

Fundamental Frequency	Baseband DAC: -2 dBFS	Baseband DAC: -6 dBFS
>3 GHz to 5 GHz	-49, typical	-50, typical
>5 GHz to 6 GHz	-44, typical	-45, typical

Conditions: two 0 dBm tones, 500 kHz apart at RF OUT.

RF gain applied to achieve the desired output power per tone.

Table 19. Third-Order Output Intermodulation Distortion (IMD₃) (dBc), -6 dBm Tones

Fundamental Frequency	Baseband DAC: -2 dBFS	Baseband DAC: -6 dBFS
65 MHz to 1.5 GHz	-50	-59
	-54, typical	-62, typical
>1.5 GHz to 3.5 GHz	-54	-59
	-57, typical	-62, typical
>3.5 GHz to 5 GHz	-50	-55
	-53, typical	-58, typical
>5 GHz to 6 GHz	-47	-51
	-50, typical	-54, typical

Conditions: two -6 dBm tones, 500 kHz apart at RF OUT.

RF gain applied to achieve the desired output power per tone.

Table 20. Third-Order Output Intermodulation Distortion (IMD₃) (dBc), -36 dBm Tones

Fundamental Frequency	Baseband DAC: -2 dBFS	Baseband DAC: -6 dBFS
65 MHz to 200 MHz	-52	-57
	-54, typical	-60, typical

Table 20. Third-Order Output Intermodulation Distortion (IMD₃) (dBc), -36 dBm Tones (Continued)

Fundamental Frequency	Baseband DAC: -2 dBFS	Baseband DAC: -6 dBFS
>200 MHz to 6 GHz	-52	-55
	-54, typical	-58, typical

Conditions: two -36 dBm tones, 500 kHz apart at RF OUT.

RF gain applied to achieve the desired output power per tone.

LO Residual Power

Table 21. VSG LO Residual Power (dBc)

Center Frequency	Self-Calibration °C ± 1 °C	Self-Calibration °C ± 5 °C
≤109 MHz	_	-50
	-60, typical	-55, typical
>109 MHz to 375 MHz	_	-45
	-65, typical	-50, typical
>375 MHz to 2 GHz	_	-55
	-67, typical	-60, typical
>2 GHz to 3 GHz	_	-50
	-60, typical	-53, typical
>3 GHz to 5 GHz	_	-55
	-65, typical	-58, typical

Table 21. VSG LO Residual Power (dBc) (Continued)

Center Frequency	Self-Calibration °C ± 1 °C	Self-Calibration °C ± 5 °C
>5 GHz to 6 GHz	_	-50
	-60, typical	-55, typical

Conditions: Configured power levels -50 dBm to +10 dBm.

This specification is valid only when the module is operating within the specified ambient temperature range and within the specified range from the last self-calibration temperature, as measured with the onboard temperature sensors.

For optimal performance, NI recommends running self-calibration when the NI 5645R temperature drifts \pm 5 °C from the temperature at the last self-calibration. For temperature changes \geq 5 °C from self-calibration, LO residual power is -40 dBc.

Figure 11. VSG LO Residual Power, 20 109 MHz to 6 GHz, Typical

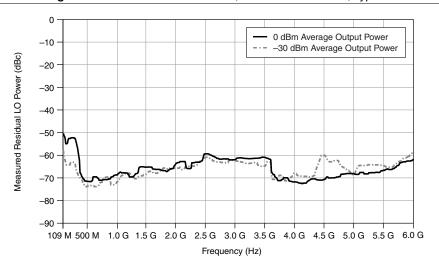


Table 22. VSG LO Residual Power (dBc), Low Power

Center Frequency	Self-Calibration °C ± 5 °C	
≤109 MHz	_	
	-49, typical	

Measurement performed after self-calibration.

Table 22. VSG LO Residual Power (dBc), Low Power (Continued)

Center Frequency	Self-Calibration °C ± 5 °C
>109 MHz to 375 MHz	-45
	-50, typical
>375 MHz to 2 GHz	-55
	-60, typical
>2 GHz to 3 GHz	-50
	-53, typical
>3 GHz to 4 GHz	-55
	-58, typical
>4 GHz to 5 GHz	_
	-40, typical
>5 GHz to 6 GHz	-43
	-45, typical

Conditions: Configured power levels < -50 dBm to -70 dBm.

This specification is valid only when the module is operating within the specified ambient temperature range and within the specified range from the last self-calibration temperature, as measured with the onboard temperature sensors.

For optimal performance, NI recommends running self-calibration when the NI 5645R temperature drifts ± 5 °C from the temperature at the last self-calibration. For temperature changes >± 5 °C from self-calibration, LO residual power is -40 dBc.

Residual Sideband Image

Table 23. VSG Residual Sideband Image (dBc), 80 MHz Bandwidth

<u> </u>		
Center Frequency	Self-Calibration °C ± 1 °C	Self-Calibration °C ± 5 °C
≤109 MHz	_	-40
	-55, typical	-45, typical
>109 MHz to 375 MHz	_	_
	-45, typical	-40, typical

Table 23. VSG Residual Sideband Image (dBc), 80 MHz Bandwidth (Continued)

Center Frequency	Self-Calibration °C ± 1 °C	Self-Calibration °C ± 5 °C
>375 MHz to 2 GHz	_	-60
	-70, typical	-65, typical
>2 GHz to 4 GHz	_	-50
	-65, typical	-55, typical
>4 GHz to 6 GHz	_	-40
	-70, typical	-50, typical

Conditions: Configured power levels -50 dBm to +10 dBm.

This specification describes the maximum residual sideband image within an 80 MHz bandwidth at a given RF center frequency. Bandwidth is restricted to 20 MHz for LO frequencies ≤ 109 MHz.

This specification is valid only when the module is operating within the specified ambient temperature range and within the specified range from the last self-calibration temperature, as measured with the onboard temperature sensors.

For optimal performance, NI recommends running self-calibration when the NI 5645R temperature drifts ± 5 °C from the temperature at the last self-calibration. For temperature changes >± 5 °C from self-calibration, residual image suppression is -40 dBc.

Figure 12. VSG Residual Sideband Image, 21 0 dBm Average Output Power, Typical

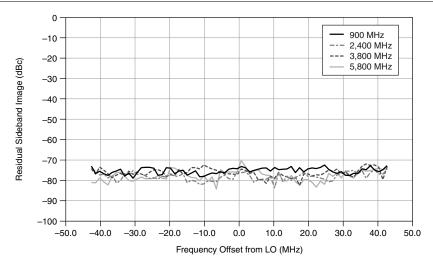
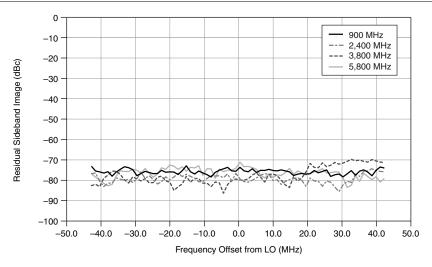


Figure 13. VSG Residual Sideband Image, 21 - 30 dBm Average Output Power, Typical



²¹ Measurement performed after self-calibration.

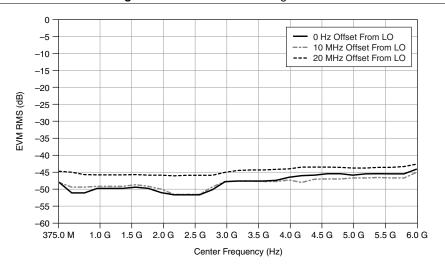
Error Vector Magnitude (EVM)

VSA EVM

20 MHz bandwidth 64-QAM EVM²² 375 MHz to 6 GHz

-40 dB

Figure 14. VSA Error Vector Magnitude²³



VSG EVM

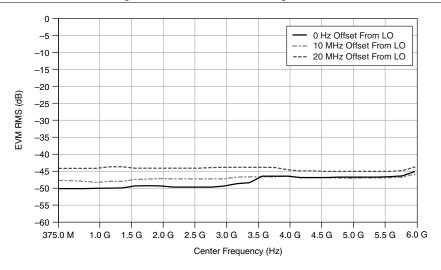
20 MHz bandwidth 64-QAM EVM²⁴ 375 MHz to 6 GHz

-40 dB

Conditions: EVM signal: 20 MHz bandwidth; 64 QAM signal. Pulse-shape filtering: root-raised-cosine, alpha=0.25; NI 5645R reference level: -10 dBm; Reference Clock source: internal; record length: 300 μs. Generator: NI PXIe-5673; power (average): -14 dBm; Reference Clock source: internal

²³ Conditions: 20 MHz bandwidth, 64 QAM; centered at LO frequency or offset digitally as listed.

²⁴ Conditions: EVM signal: 20 MHz bandwidth; 64 QAM signal. Pulse-shape filtering: root-raised cosine, alpha=0.25; NI 5645R peak output power: -10 dBm; Reference Clock source: internal. Measurement instrument: NI PXIe-5665; reference level: -10 dBm; Reference Clock source: internal; record length: 300 μs.



I/Q Interface

Differential and Single-Ended Operation

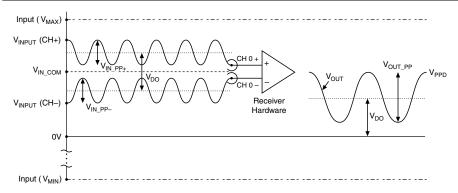
The I/Q inputs and outputs of the NI 5645R support both single-ended and differential operation. This section explains some of the fundamental analog signal processing that occurs in the first stages of the I/Q receiver.

A differential signal system has a positive component (V_{INPUT}(CH+)) and a negative component $(V_{INPLIT}(CH-))$. The differential signal can have a common-mode offset (V_{IN-COM}) shared by both $V_{INPUT}(CH+)$ and $V_{INPUT}(CH-)$. The differential input signal is superimposed on the common-mode offset. The input circuitry rejects the input common-mode offset signal.

In a differential system, any noise present on both V_{INPUT}(CH+) and V_{INPUT}(CH-) gets rejected. Differential systems also double the dynamic range compared to a single-ended system with the same voltage swing. The following figure illustrates the key concepts of differential offset and common-mode offset associated with a differential system.

Conditions: 20 MHz bandwidth, 64 QAM; centered at LO frequency or offset digitally as listed.

Figure 16. Definition of Common-Mode Offset and Differential Offset



where

 $V_{IN_PP^+}$ represents the peak-to-peak amplitude of the positive AC input signal $V_{IN_PP^-}$ represents the peak-to-peak amplitude of the negative AC input signal

V_{DO} represents the differential offset voltage

V_{IN COM} represents the common-mode offset voltage

V_{OUT PP} represents the peak-to-peak amplitude of the output signal

In the previous figure, the input common-mode voltage is not present after the first stage of the receiver system. The signal remaining at the output of the receiver circuitry is the signal of interest.



Note The differential signal can have an offset between $V_{INPUT}(CH+)$ and $V_{INPUT}(CH-)$. This is known as the *differential offset* and is retained by the receiver circuitry.

In an I/Q analyzer, a differential offset can occur because of LO leakage or harmonics. In the case of I/Q generation, a differential offset can cause spurs and magnitude error.

In a phase-balanced differential system, the peak-to-peak amplitude of the positive AC input signal (V_{IN_PP+}) is equal to the peak-to-peak amplitude of the negative AC input signal (V_{IN_PP+}). The AC peak-to-peak amplitude of the output signal is the sum of V_{IN_PP+} and V_{IN_PP-} . A more general definition for the output voltage regardless of phase is the difference between V_{IN_PP+} and V_{IN_PP-} described by the following equation:

$$V_{OUT} = (V_{INPUT}(CH+)) - (V_{INPUT}(CH-))$$

The common-mode offset, which represents the rejected component common to both signals, is described by the following equation:

$$V_{IN_COM} = [(V_{INPUT}(CH+)) + (V_{INPUT}(CH-))]/2$$

Related Information

Refer to the NI RF Vector Signal Transceivers Help for more information about differential and single-ended operation on the NI 5645R.

I/Q Input

Vertical Range

Maximum input voltage	
Maximum functional voltage	± 2.5 V, typical
Maximum input voltage ²⁶ (damage)	±3 V
Common-mode range ²⁷	±2 V
Differential voltage range	
Analog	$0.032~V_{pk-pk}$ to $2~V_{pk-pk}$
Digital	<0.032 V _{pk-pk}
Single-ended voltage range ²⁸	
Analog	$0.032~V_{pk-pk}$ to $2~V_{pk-pk}$
Digital	<0.032 V _{pk-pk}
Analog gain step range	36 dB
Gain step resolution	1 dB, typical

Absolute DC Gain Accuracy

Table 24. I/Q Input Absolute DC Gain Error

Temperature Range	Absolute Gain Error	
Within ±5 °C of 23 °C	±1.75%	
	±1.10%, typical	

²⁶ Common-mode voltage plus peak AC voltage cannot exceed the maximum input voltage of 2.5 V.

²⁷ Common-mode voltage plus peak AC voltage cannot exceed the maximum input voltage of 2.5 V. Valid for all differential levels.

²⁸ To use the I or Q channel in single-ended terminal configuration, connect the positive (+) terminal to the active signal and terminate the negative (-) terminal with a 50 Ω termination.

Table 24. I/Q Input Absolute DC Gain Error (Continued)

Temperature Range	Absolute Gain Error	
Outside ±5 °C of 23°C	-0.033%/°C	
	-0.027%/°C, typical	

The accuracy of a measured DC signal using the 0.5 V differential input range is calculated using the following equations:

Gain accuracy for temperature within ±5 °C of ambient 23 °C:

$$\pm (1.75\% \times 0.5 \text{ V}) = \pm 8.75 \text{ mV}$$

Gain accuracy for a temperature at +20 °C above ambient 23 °C:

 $\pm 8.75 \text{ mV} - 0.033\% \times 15 \text{ °C} \times (0.5) = +6.28 \text{ mV}/-11.23 \text{ mV}$

Table 25. I/Q Input DC Offset Error (mV)

Temperature Range	I/Q Input DC Offset Error	
23 °C ± 5 °C	±15	
	±6, typical	
0 °C to 55 °C	±20	
	±10, typical	

Absolute AC Gain Accuracy

Table 26. I/Q Input Absolute AC Gain Accuracy²⁹ (dB)

Input Range	23 °C ± 5 °C	0 °C to 55 °C
2 V _{pk-pk}	0.42	0.47
	0.1, typical	0.16, typical
0.5 V _{pk-pk}	0.41	0.47
	0.1, typical	0.16, typical
0.1 V _{pk-pk}	0.52	0.60
	0.1, typical	0.23, typical

²⁹ Configured for 0 V common-mode, differential. Measured CW at 500 kHz.

Complex Equalized Bandwidth

Complex I/Q equalized bandwidth ³⁰	80 MHz
Bandwidth (equalization enabled or disabled)	
Baseband	40 MHz
Complex baseband	80 MHz when used with an external I/Q modulator



Note To operate the device in complex baseband mode, configure each channel with identical ranges and termination. Complex baseband mode requires two input signals that are 90° out of phase.

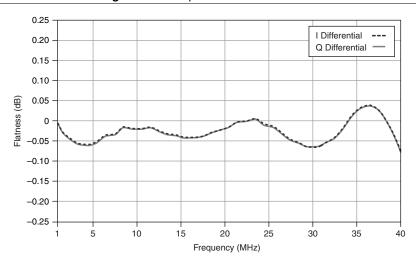
Passband Flatness

Table 27. I/Q Input Passband Flatness³¹ (dB)

I or Q Bandwidth	23 °C ± 5 °C	0 °C to 55 °C
20 MHz	0.43	0.49
	0.15, typical	0.21, typical
40 MHz	0.52	0.58
	0.21, typical	0.27, typical

³⁰ Complex equalized bandwidth is the combined bandwidth of I and Q channels. Valid only when using identical gain and termination settings for each I/Q channel.

³¹ Referenced to 500 kHz. Digital equalization enabled. Valid only when using identical gain and termination settings for each I/Q channel.



Channel-to-Channel Gain Imbalance

Table 28. I/Q Input Gain Imbalance³² (dB)

rable 20. I/Q input dail imbalance (ab)		
Complex Bandwidth	23 °C ± 5 °C	0 °C to 55 °C
40 MHz	± 0.025	± 0.06
	± 0.02, typical	± 0.04, typical
80 MHz	± 0.045	± 0.075
	± 0.03, typical	± 0.05, typical

Channel-to-Channel Phase Matching

Table 29. I/Q Input Phase Matching³³ (Degrees)

Complex Bandwidth	23 °C ± 5 °C	0 °C to 55 °C
40 MHz	± 0.10	± 0.3
	± 0.06, typical	± 0.16, typical

³² Digital equalization enabled. Valid only when using identical gain and termination settings for each I/Q channel.

³³ Digital equalization enabled. Valid only when using identical gain and termination settings for each I/Q channel.

Table 29. I/Q Input Phase Matching³³ (Degrees) (Continued)

Complex Bandwidth	23 °C ± 5 °C	0 °C to 55 °C
80 MHz	± 0.16	± 0.5
	± 0.10, typical	± 0.35, typical

Image Suppression

Table 30. I/Q Input Image Suppression³⁴ (dBc)

Complex Bandwidth	23 °C ± 5 °C
40 MHz	-60
	-63, typical
80 MHz	-57
	-60, typical

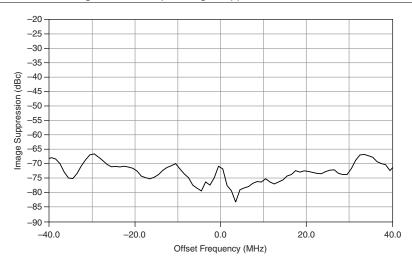
Image suppression is equivalent or better than specification at all frequency offsets within the specified bandwidth.

For ambient temperatures from 0 °C to 55 °C, image suppression is -50 dBc, typical over 80 MHz of complex bandwidth. External calibration is recommended to optimize performance for a specific ambient temperature outside of 23 °C \pm 5 °C.

³³ Digital equalization enabled. Valid only when using identical gain and termination settings for each I/Q channel.

³⁴ Digital equalization enabled. Valid only when using identical gain and termination settings for each I/Q channel.

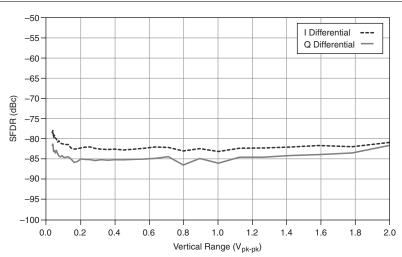
Figure 18. I/Q Input Image Suppression, 35 Nominal



Spectral Characteristics

Spurious Free Dynamic Range (SFDR)

Figure 19. Measured I/Q Input SFDR³⁶



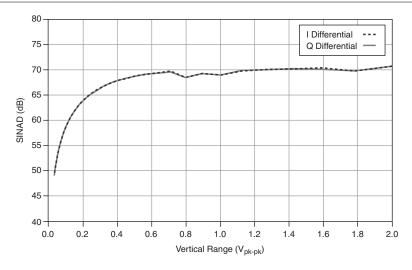
³⁵ Measured at 23 °C. Valid only when using identical gain and termination settings for each I/Q channel

³⁶ Measured with a -1 dBFS tone at 9.9 MHz.

Signal to Noise and Distortion (SINAD)

I/Q input SINAD ³⁷ (dB)		
23 °C ± 5 °C	69, typical	
0 °C to 55 °C	67, typical	

Figure 20. Measured I/Q Input SINAD37

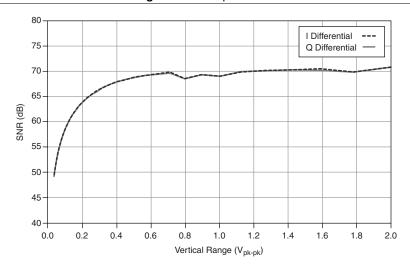


Signal-to-Noise Ratio (SNR)

` `	•
I/Q input SNR ³⁸ (dB)	
23 °C ± 5 °C	69, typical
0 °C to 55 °C	67, typical

Measured with a fixed -1 dBFS input signal at 9.9 MHz. Specification is valid within 20 MHz of bandwidth for I or Q.

³⁸ Measured with a -1 dBFS input signal at 9.9 MHz. Specification is valid within 20 MHz of bandwidth for I or Q.



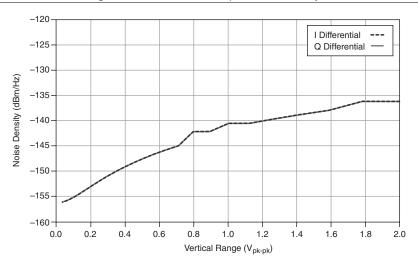
Average Noise Density

I/Q input average noise density³⁹ (dBm/Hz)

23 °C ± 5 °C	-147, typical	
0 °C to 55 °C	-146, typical	

³⁹ Measured in the presence of a -40 dBFS signal.

Figure 22. Measured I/Q Input Noise Density³⁹



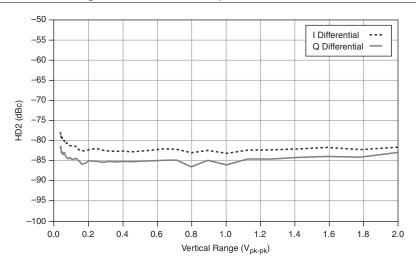
Harmonics

I/O input second harmonic⁴⁰ (dBc)

2 4 mput second numbers (app)		
$23 ^{\circ}\text{C} \pm 5 ^{\circ}\text{C}$	-76, typical	
0 °C to 55 °C	-75, typical	

⁴⁰ Measured with a -1 dBFS input signal at 9.9 MHz.

Figure 23. Measured I/Q Input Second Harmonic⁴⁰



I/Q input	third	harmonic ⁴⁰	(dBc)

23 °C ± 5 °C	-80, typical
0 °C to 55 °C	-79, typical

Figure 24. Measured I/Q Input Third Harmonic⁴⁰

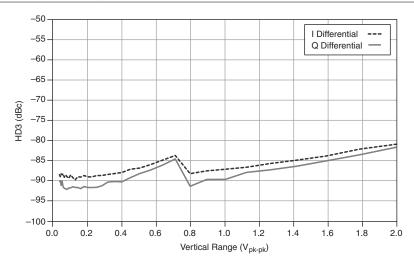
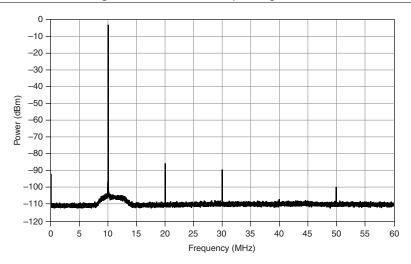


Figure 25. Measured I/Q Input Single Tone⁴¹



Third-Order Input Intermodulation

I/Q third-order input intermodulation⁴² (IMD₃) (dBc)

23 °C ± 5 °C	-80, typical
0 °C to 55 °C	-79, typical

⁴¹ Measured with 10 MHz bandpass filter to remove stimulus-related noise and distortion.

⁴² Measured with two-tone stimulus; each tone is -7 dBFS with a 200 kHz spacing; 9.9 MHz and 10.1 MHz tone frequencies.

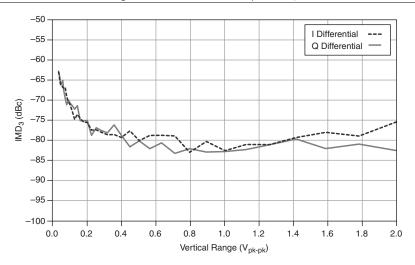
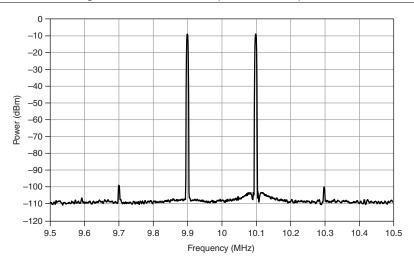


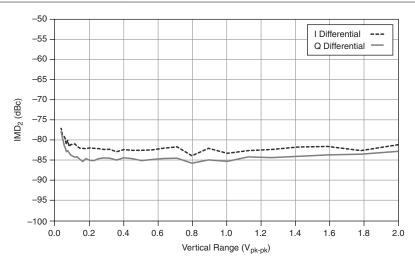
Figure 27. Measured I/Q Input Two-Tone Spectrum



Second-Order Input Intermodulation

i Q second order input intermodulation	(INIB2) (abe)	
23 °C ± 5 °C	-77, typical	
0 °C to 55 °C	-75, typical	

Figure 28. Measured I/Q Input IMD₂⁴³



I/Q Output

Output Range⁴⁴

Maximum output voltage	±2.5 V
Common-mode range ⁴⁵	±2 V
Differential voltage range	
Analog	$0.032V_{pk-pk}$ to $2\ V_{pk-pk}$
Digital	$< 0.032 \text{ V}_{\text{pk-pk}}$

Measured with two-tone stimulus; each tone is -7 dBFS with a 200 kHz spacing; 9.9 MHz and 10.1 MHz tone frequencies.

⁴⁴ High-impedance load.

⁴⁵ Valid for all differential levels.

Single-ended voltage range⁴⁶

Analog	$0.016~V_{pk-pk}$ to $1~V_{pk-pk}$
Digital	$< 0.016 \text{ V}_{\text{pk-pk}}$
Analog gain step range	36 dB
Gain step resolution	1 dB, typical

Absolute DC Gain Accuracy

Table 31. I/Q Output Absolute DC Gain Error⁴⁷

Temperature Range	Absolute Gain Error
Within ±5 °C of 23 °C	±1.12%
	±0.62%, typical
Outside ±5 °C of 23°C	-0.055%/°C
	-0.045%/°C, typical

The accuracy of a measured DC signal using the 0.5 V differential output range is calculated using the following equations:

Gain accuracy for temperature within ± 5 °C of ambient 23 °C: $\pm (1.12\% \times 0.5 \text{ V}) = \pm 5.6 \text{ mV}$

Gain accuracy for a temperature at +20 °C above ambient 23 °C:

 $\pm 5.6 \text{ mV} - 0.055\% \times 15 \text{ °C} \times (0.5) = +1.5 \text{ mV/-}9.8 \text{ mV}$

Table 32. I/Q Output DC Offset Error⁴⁸ (mV)

Temperature Range	I/Q Output DC Offset Error
23 °C ± 5 °C	±3.6
	±2.5, typical
0 °C to 55 °C	±4.5
	±2.9, typical

⁴⁶ To use the I or Q channel in single-ended terminal configuration, connect the positive (+) terminal to the active signal and terminate the negative (-) terminal with a 50 Ω termination.

⁴⁷ Measured with a DMM. Measured with both output terminals terminated to ground through a high impedance.

⁴⁸ High-impedance load.

⁴⁹ Configured for 0 V common-mode, differential. Measured CW at 500 kHz.

Absolute AC Gain Accuracy

Table 33. I/Q Output Absolute AC Gain Accuracy⁴⁹ (dB)

Output Range	23 °C ± 5 °C	0 °C to 55 °C
1.0 V _{pk-pk}	0.48	0.53
	0.13, typical	0.19, typical
0.5 V _{pk-pk}	0.47	0.52
	0.13, typical	0.19, typical
0.1 V _{pk-pk}	0.57	0.64
	0.15, typical	0.22, typical

Complex Equalized Bandwidth

•	
Complex I/Q equalized bandwidth ⁵⁰	80 MHz
Bandwidth (equalization enabled)	
Baseband	40 MHz
Complex baseband	80 MHz when used with an external
	I/Q modulator



Note To operate the device in complex baseband mode, configure each channel with identical ranges and termination. Complex baseband mode requires two input signals that are 90° out of phase.

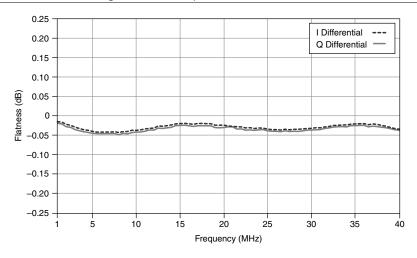
Passband Flatness

Table 34. I/Q Output Passband Flatness⁵¹ (dB)

I or Q Bandwidth	23 °C ± 5 °C	0 °C to 55 °C
20 MHz	0.42	0.48
	0.13, typical	0.19, typical
40 MHz	0.43	0.49
	0.14, typical	0.20, typical

⁵⁰ Complex equalized bandwidth is the combined bandwidth of I and Q channels. Valid only when using identical gain and termination settings for each I/Q channel.

⁵¹ Referenced to 500 kHz. Valid only when using identical gain and termination settings for each I/Q channel.



Channel-to-Channel Gain Imbalance

Table 35. I/Q Output Gain Imbalance⁵² (dB)

Complex Bandwidth	23 °C ± 5 °C	0 °C to 55 °C
40 MHz	0.02	0.06
	0.015, typical	0.04, typical
80 MHz	0.025	0.065
	0.02, typical	0.045, typical

Channel-to-Channel Phase Matching

Table 36. I/Q Output Phase Matching⁵³ (Degrees)

Complex Bandwidth	23 °C ± 5 °C	0 °C to 55 °C
40 MHz	0.1	0.15
	0.05, typical	0.1, typical
80 MHz	0.125	0.15
	0.08, typical	0.1, typical

⁵² Valid only when using identical gain and termination settings for each I/Q channel.

⁵³ Valid only when using identical gain and termination settings for each I/Q channel.

Image Suppression

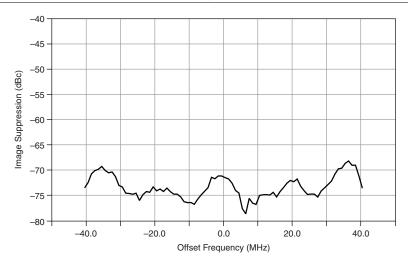
Table 37. I/Q Output Image Suppression⁵⁴ (dBc)

Complex Bandwidth	23 °C ± 5 °C
40 MHz	-62
	-65, typical
80 MHz	-55
	-60, typical

Image suppression is equivalent or better than specification at all frequency offsets within the specified bandwidth.

For ambient temperatures from 0 °C to 55 °C, image suppression is -50 dBc, typical over 80 MHz of complex bandwidth. External calibration is recommended to optimize performance for a specific ambient temperature outside of 23 °C \pm 5 °C.

Figure 30. I/Q Output Image Suppression, Nominal

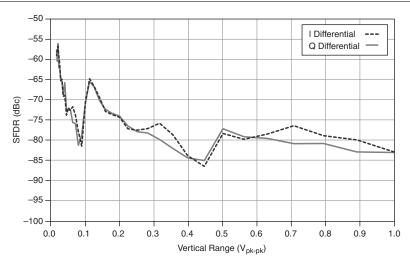


⁵⁴ Digital equalization enabled. Valid only when using identical gain and termination settings for each I/Q channel.

Spectral Characteristics

SFDR

Figure 31. Measured I/Q Output SFDR, 9.9 MHz Signal

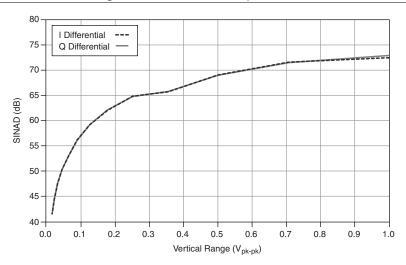


SINAD

I/Q output SINAD ⁵⁵ (dB)		
23 °C ± 5 °C	66, typical	
0 °C to 55 °C	64, typical	

⁵⁵ Generated -1 dBFS CW at 9.9 MHz. Includes harmonic and nonharmonic content. Short pattern waveforms may degrade the distortion performance by 3 dB.

Figure 32. Measured I/Q Output SINAD55

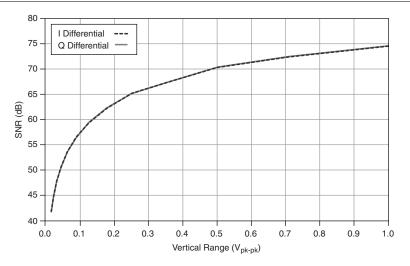


SNR

I/Q output SNR ⁵⁶ (dB)		
23 °C ± 5 °C	66, typical	
0 °C to 55 °C	64, typical	

⁵⁶ Generated -1 dBFS CW at 9.9 MHz.

Figure 33. Measured I/Q Output SNR⁵⁶



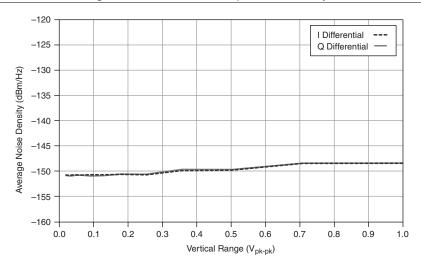
Average Noise Density

I/Q output average noise density⁵⁷ (dBm/Hz)

23 °C ± 5 °C	-149, typical	
0 °C to 55 °C	-147, typical	

⁵⁷ Terminated into 50 Ω .

Figure 34. Measured I/Q Output Noise Density⁵⁷



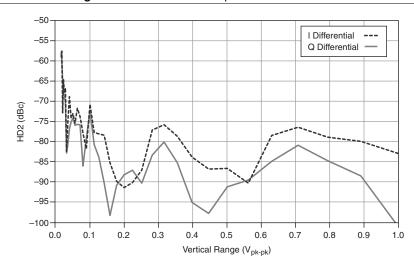
Harmonics

I/O output second harmonic⁵⁸ (dBc)

i Q output second narmonic (an	v)	
23 °C ± 5 °C	-75, typical	
0 °C to 55 °C	-73, typical	

⁵⁸ Generated -1 dBFS CW at 9.9 MHz.

Figure 35. Measured I/Q Output Second Harmonic⁵⁸



I/Q output third harmonic⁵⁸ (dBc)

23 °C ± 5 °C	-84, typical
0 °C to 55 °C	-83, typical

Figure 36. Measured I/Q Output Third Harmonic⁵⁸

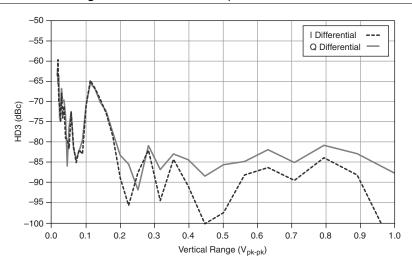
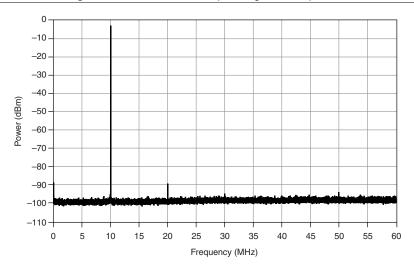


Figure 37. Measured I/Q Output Single Tone Spectrum



Third-Order Output Intermodulation

I/Q third-order output intermodulation⁵⁹ (IMD₃) (dBc)

23 °C ± 5 °C	-80, typical	
0 °C to 55 °C	-75, typical	

⁵⁹ Generating -7 dBFS CW tones at 9.9 MHz and 10.1 MHz.

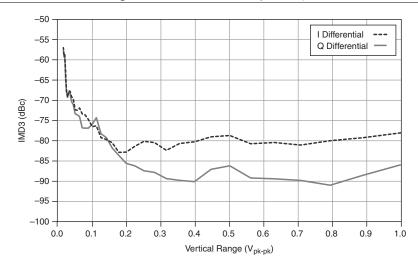
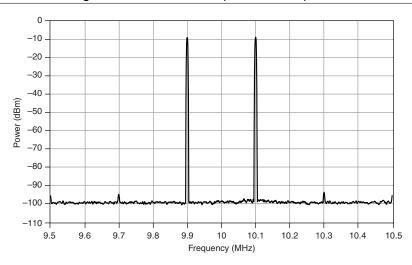


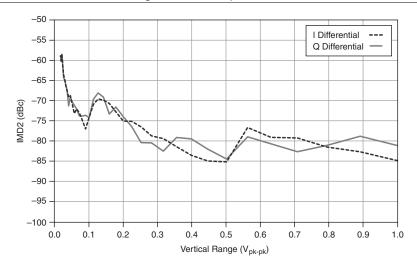
Figure 39. Measured I/Q Output Two-Tone Spectrum



Second-Order Output Intermodulation

I/Q second-order output intermodulation⁶⁰ (IMD₂) (dBc) $23 \text{ °C} \pm 5 \text{ °C} \qquad -80, \text{ typical}$ $0 \text{ °C to 55 °C} \qquad -75, \text{ typical}$

 $^{^{60}\,\,}$ Generating -1 dBFS CW tones at 9.9 MHz and 10.1 MHz.



Application-Specific Modulation Quality

Typical performance assumes the NI 5645R is operating within ± 5 °C of the previous selfcalibration temperature, and that the ambient temperature is 0 °C to 55 °C.

RF Application-Specific Modulation Quality

WLAN 802.11ac

OFDM61

-45 EVM (rms) dB, typical

WI AN 802.11n

Table 38. 802.11n OFDM EVM (rms) (dB), Typical

Frequency	20 MHz Bandwidth	40 MHz Bandwidth
2,412 MHz	-50	-50
5,000 MHz	-48	-46

Conditions: RF OUT loopback to RF IN; average power: -10 dBm; reference level: autoleveled based on real-time average power measurement; 20 packets; 3/4 coding rate; 64 OAM.

⁶¹ Conditions: RF OUT loopback to RF IN; 5,800 MHz; 80 MHz bandwidth; average power: -30 dBm to -5 dBm; 20 packets; 16 OFDM data symbols; MCS=9; 256 QAM.

WLAN 802.11a/g/j/p

Table 39. 802.11a/g/j/p OFDM EVM (rms) (dB), Typical

Frequency	20 MHz Bandwidth
2,412 MHz	-53
5,000 MHz	-50

Conditions: RF OUT loopback to RF IN; average power: -10 dBm; reference level: auto-leveled based on real-time average power measurement; 20 packets; 3/4 coding rate; 64 QAM.

WLAN 802.11g

Table 40. 802.11g DSSS-OFDM EVM (rms) (dB), Typical

Frequency	20 MHz Bandwidth
2,412 MHz	-53
5,000 MHz	-50

Conditions: RF OUT loopback to RF IN; average power: -10 dBm; reference level: auto-leveled based on real-time average power measurement; 20 packets; 3/4 coding rate; 64 QAM.

WLAN 802.11b/g

DSSS ⁶² -48 EVM (rms) dB, typical
--

LTE

Table 41. SC-FDMA⁶³ (Uplink FDD) EVM (rms) (dB), Typical

Frequency	5 MHz Bandwidth	10 MHz Bandwidth	20 MHz Bandwidth
700 MHz	-56	-56	-54
900 MHz	-55	-55	-53
1,430 MHz	-54	-54	-53
1,750 MHz	-51	-50	-50

⁶² Conditions: RF OUT loopback to RF IN; 2,412 MHz; 20 MHz bandwidth; average power -10 dBm; reference level: auto-leveled based on real-time average power measurement; averages: 10; pulse-shaping filter: Gaussian reference; CCK 11 Mbps.

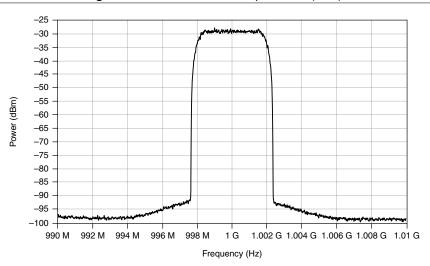
⁶³ Single channel uplink only.

Table 41. SC-FDMA⁶³ (Uplink FDD) EVM (rms) (dB), Typical (Continued)

Frequency	5 MHz Bandwidth	10 MHz Bandwidth	20 MHz Bandwidth
1,900 MHz	-51	-50	-50
2,500 MHz	-50	-49	-49

WCDMA

Figure 41. WCDMA Measured Spectrum⁶⁴ (ACP)



I/Q Baseband Application-Specific Modulation Quality

WLAN 802.11ac

OFDM ⁶⁵ -53 EVM (rms) dB, nominal	
WLAN 802.11n	
OFDM ⁶⁶	-54 EVM (rms) dB, nominal

⁶³ Single channel uplink only.

⁶⁴ Conditions: DL Test Model 1 (64DPCH); RF output level: -10 dBm average; RF OUT loopback to RF IN; measured results better than -66 dB.

⁶⁵ Conditions: I/Q OUT loopback to I/Q IN; $0.5~V_{pk-pk}$ range, differential; 80~MHz bandwidth; 20 packets; 16 OFDM data symbols; MCS=9; 256 QAM.

 $^{^{66}}$ Conditions: I/Q OUT loopback to I/Q IN; 0.5 $V_{pk\text{-}pk}$ range, differential; 20 MHz, 40 MHz bandwidth; 20 packets; 3/4 coding rate; 64 QAM.

WLAN 802.11a/g/j/p

0 , .	
OFDM ⁶⁷	-58 EVM (rms) dB, nominal
WLAN 802.11g	
DSSS-OFDM ⁶⁸	-56 EVM (rms) dB, nominal
WLAN 802.11b/g	
DSSS ⁶⁹	-51 EVM (rms) dB, nominal
LTE	
SC-FDMA ⁷⁰ (Uplink FDD)	-56 channel EVM (rms) dB, nominal

Baseband Characteristics

Resolution	16 bits
Sample rate ⁷¹	120 MS/s
I/Q data rate ⁷²	1.84 kS/s to 120 MS/s
gital-to-analog converters (DAC	Cs)
Resolution	16 bits
Sample rate ⁷³	120 MS/s
I/Q data rate ⁷⁴	1.84 kS/s to 120 MS/s

Onboard FPGA

FPGA	Xilinx Virtex-6 LX195T
LUTs	124,800

⁶⁷ Conditions: I/Q OUT loopback to I/Q IN; 0.5 V_{pk-pk} range, differential; 20 MHz bandwidth; 20 packets; 3/4 coding rate; 64 QAM.

⁶⁸ Conditions: I/Q OUT loopback to I/Q IN; 0.5 V_{pk-pk} range, differential; 20 MHz bandwidth; 20 packets; 3/4 coding rate; 64 QAM.

⁶⁹ Conditions: I/Q OUT loopback to I/Q IN; 0.5 V_{pk-pk} range, differential; 20 MHz bandwidth; Averages: 10; Pulse shaping filter: Gaussian; CCK: 11 Mbps.

⁷⁰ Conditions: I/Q OUT loopback to I/Q IN; 0.5 V_{pk-pk} range, differential; 5 MHz, 10 MHz, 20 MHz bandwidth; single channel uplink only; 64 QAM PUSCH modulation.

ADCs are dual-channel components with each channel assigned to I and Q, respectively.

⁷² I/Q data rates lower than 120 MS/s are achieved using fractional decimation.

⁷³ DACs are dual-channel components with each channel assigned to I and Q, respectively. DAC sample rate is internally interpolated to 960 MS/s, automatically configured.

⁷⁴ I/Q data rates lower than 120 MS/s are achieved using fractional interpolation.

Flip-flops	249,600
DSP48 slices	640
Embedded block RAM	12,384 kbits
Data transfers	DMA, interrupts, programmed I/O
Number of DMA channels	16

Onboard DRAM

Memory size	2 banks, 256 MB per bank
Theoretical maximum data rate	2.1 GB/s per bank

Onboard SRAM

Memory size	2 MB
Maximum data rate (read)	40 MB/s
Maximum data rate (write)	36 MB/s

Front Panel I/O

RFIN

Connector	SMA (female)
Input impedance	50 Ω , nominal, AC coupled
Maximum DC input voltage without damage	8 V
Absolute maximum input power ⁷⁵	+33 dBm (CW RMS)

Input Return Loss (Voltage Standing Wave Ratio (VSWR))

Table 42. Input Return Loss (dB) (VSWR)

Frequency	Typical
109 MHz ≤ <i>f</i> < 2.4 GHz	15.5 (1.40:1)
2.4 GHz ≤ f < 4 GHz	12.7 (1.60:1)
$4 \text{ GHz} \le f \le 6 \text{ GHz}$	11.0 (1.78:1)
Return loss for frequencies <109 MHz is typically better than 14 dB (VSWR <1.5:1).	

 $^{^{75}}$ For modulated signals, peak instantaneous power not to exceed +36 dBm.

RF OUT

Connector	SMA (female)
Output impedance	50 Ω, nominal, AC coupled
Absolute maximum reverse power ⁷⁶	
<4 GHz	+33 dBm (CW RMS)
≥4 GHz	+30 dBm (CW RMS)

Output Return Loss (VSWR)

Table 43. Output Return Loss (dB) (VSWR)

Frequency	Typical
109 MHz ≤ f < 2 GHz	19.0 (1.25:1)
$2 \text{ GHz} \leq f < 5 \text{ GHz}$	14.0 (1.50:1)
$5 \text{ GHz} \le f \le 6 \text{ GHz}$ $11.0 (1.78:1)$	
Return loss for frequencies <109 MHz is typically better than 20 dB (VSWR <1.22:1).	

CAL IN, CAL OUT

Connector	SMA (female)
Impedance	50 Ω, nominal



Caution Do not disconnect the cable that connects CAL IN to CAL OUT. Removing the cable from or tampering with the CAL IN or CAL OUT front panel connectors voids the product calibration and specifications are no longer warranted.

LO OUT (RF IN 0 and RF OUT 0)

Connectors	SMA (female)
Frequency range ⁷⁷	65 MHz to 6 GHz
Power	
LO OUT (RF IN 0) 65 MHz to 6 GHz	0 dBm ±2 dB, typical

⁷⁶ For modulated signals, peak instantaneous power not to exceed corresponding peak power of specified CW.

When tuning to 65 MHz to 375 MHz using the RF IN channel, the exported LO is twice the RF frequency requested.

LO OUT (RF OUT 0)

65 MHz to 3.6 GHz	0 dBm ±2 dB, typical
≥3.6 GHz to 6 GHz	3 dBm ±2 dB, typical
Output power resolution	0.25 dB, nominal
Output impedance	50 Ω , nominal, AC coupled
Output return loss	>11.0 dB (VSWR <1.8:1), typical
Output isolation (state: disabled)	
<2.5 GHz tuned LO	-45 dBc, nominal
≥2.5 GHz tuned LO	-35 dBc, nominal

LO IN (RF IN 0 and RF OUT 0)

Connectors	SMA (female)
Frequency range ⁷⁸	65 MHz to 6 GHz
Expected input power	
LO IN (RF IN 0) 65 MHz to 6 GHz	0 dBm ±3 dB, nominal
LO IN (RF OUT 0)	
65 MHz to 3.6 GHz	0 dBm ±3 dB, nominal
\geq 3.6 GHz to 6 GHz	3 dBm ±1 dB, nominal
Input impedance	50 Ω , nominal, AC coupled
Input return loss	>11.7 dB (VSWR <1.7:1), typical
Absolute maximum power	+15 dBm
Maximum DC voltage	±5 VDC

I/Q IN 0

Connectors	MCX
DC input resistance	
Single-ended	50 Ω , nominal
Differential	100 Ω , nominal
Input coupling, per terminal	DC
Input return loss ≤ 40 MHz	>-28 dB, nominal

 $^{^{78}\,}$ When tuning to 65 MHz to 375 MHz using the RF IN channel, the exported LO is twice the RF frequency requested.

Input type	Single-ended ⁷⁹ , differential
Number of channels	2
I/Q OUT 0	
Connectors	MCX
DC output resistance	
Single-ended	50 Ω, nominal
Differential	100 Ω , nominal
Output coupling, per terminal	DC
Output return loss ≤ 40 MHz	>-28 dB, nominal
Output type	Single-ended ⁸⁰ , differential
Number of channels	2
REF IN	
Connector	SMA (female)
Frequency	10 MHz
Tolerance ⁸¹	$\pm 10 \times 10^{-6}$
Amplitude	
Square	$0.7~V_{pk\text{-}pk}$ to $5.0~V_{pk\text{-}pk}$ into $50~\Omega$, typical
Sine ⁸²	1.4 V_{pk-pk} to 5.0 V_{pk-pk} into 50 Ω , typical
Input impedance	50 Ω, nominal
Coupling	AC
REF OUT	
Connector	SMA (female)
Frequency	
Reference Clock ⁸³	10 MHz, nominal
Sample Clock	120 MHz, nominal
Amplitude	1.65 V_{pk-pk} into 50 Ω, nominal

⁷⁹ Negative terminal must be externally terminated in single-ended mode.

Negative terminal must be externally terminated in single-ended mode.

Frequency accuracy = tolerance \times reference frequency

 $^{^{82}}$ 1 V_{rms} to 3.5 V_{rms} , typical. Jitter performance improves with increased slew rate of input signal.

Refer to the *Internal Frequency Reference* for accuracy.

Output impedance	50 Ω , nominal
Coupling	AC
PFI 0	
Connector	SMA (female)
Voltage levels ⁸⁴	
Absolute maximum input range	-0.5 V to 5.5 V
$ m V_{IL}$	0.8 V
$V_{ m IH}$	2.0 V
$V_{ m OL}$	0.2 V with 100 μA load
V_{OH}	2.9 V with 100 μA load
Input impedance	10 kΩ, nominal
Output impedance	50 Ω, nominal
Maximum DC drive strength	24 mA

DIGITAL I/O

Connector VHDCI

Minimum required direction change latency⁸⁵ 48 ns + 1 clock cycle

Table 44. DIGITAL I/O Signal Characteristics

Signal	Direction	Port Width
DIO <2320>	Bidirectional, per port	4
DIO <1916>	Bidirectional, per port	4
DIO <1512>	Bidirectional, per port	4
DIO <118>	Bidirectional, per port	4
DIO <74>	Bidirectional, per port	4
DIO <30>	Bidirectional, per port	4
PFI 1	Bidirectional	1
PFI 2	Bidirectional	1

 $^{^{84}}$ Voltage levels are guaranteed by design through the digital buffer specifications.

⁸⁵ Clock cycle refers to the FPGA clock domain used for direction control.

Table 44. DIGITAL I/O Signal Characteristics (Continued)

Signal	Direction	Port Width
Clock In	Input	1
Clock Out	Output	1

Voltage levels ⁸⁶	
Absolute maximum input range	-0.5 V to 4.5 V
$ m V_{IL}$	0.8 V
$ m V_{IH}$	2.0 V
$V_{ m OL}$	0.2 V with 100 μA load
V_{OH}	2.9 V with 100 µA load
Input impedance	
DIO <230>, CLK IN	$10 \text{ k}\Omega$, nominal
PFI 1, PFI 2	$100 \ k\Omega$ pull up, nominal
Output impedance	50 Ω, nominal
Maximum DC drive strength	12 mA
Minimum required direction change latency ⁸⁷	48 ns + 1 clock cycle
Maximum toggle rate	125 MHz, typical

Voltage levels are guaranteed by design through the digital buffer specifications.
 Clock cycle refers to the FPGA clock domain used for direction control.

)
NC	1	35	NC
GND	2	36	GND
NC	3	37	NC
GND	4	38	GND
NC	5	39	NC
GND	6	40	GND
NC	7	41	NC
RESERVED	8	42	GND
DIO 23	9	43	DIO 22
GND	10	44	GND
DIO 21	11	45	DIO 20
GND	12	46	GND
DIO 19	13	47	DIO 18
GND	14	48	GND
DIO 17	15	49	DIO 16
GND	16	50	GND
DIO 15	17	51	DIO 14
GND	18	52	RESERVED
DIO 13	19	53	DIO 12
GND	20	54	GND
DIO 11	21	55	DIO 10
GND	22	56	GND
DIO 9	23	57	DIO 8
GND	24	58	GND
DIO 7	25	59	DIO 6
PFI 1	26	60	RESERVED
DIO 5	27	61	DIO 4
GND	28	62	GND
DIO 3	29	63	DIO 2
NC	30	64	PFI 2
DIO 1	31	65	DIO 0
GND	32	66	GND
CLK OUT	33	67	CLK IN
GND	34	68	GND
			/

Power Requirements

Table 45. Power Requirements

Voltage (V _{DC})	Typical Current (A)	Maximum Current (A)
+3.3	4.9	5.3
+12	3.3	4.2

Power is 56 W, typical. Consumption is from both NI PXI Express backplane power connectors.

Calibration

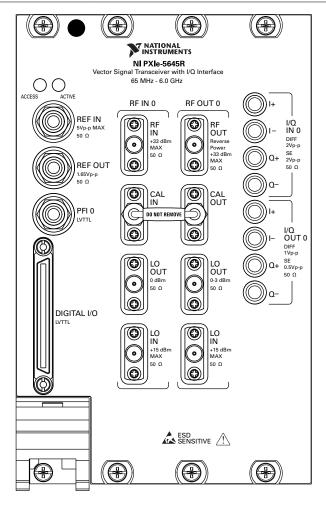
Interval 1 year



Note For the two-year calibration interval, add 0.2 dB to one-year specifications for Absolute Amplitude Accuracy, RF input Frequency Response, Output Power Level Accuracy, and RF output Frequency Response.

Hardware Front Panel

Figure 43. NI 5645R Front Panel



Physical Characteristics

NI 5645R module	3U, four slot, PXI Express module $8.1 \text{ cm} \times 12.9 \text{ cm} \times 21.1 \text{ cm}$ $3.2 \text{ in} \times 5.6 \text{ in} \times 8.3 \text{ in}$
Weight	1,758 g (62.0 oz)

Environment

Maximum altitude	2,000 m (800 mbar) (at 25 °C ambient temperature)
Pollution Degree	2

Indoor use only.

Operating Environment

Ambient temperature range	0 °C to 55 °C (Tested in accordance with IEC 60068-2-1 and IEC 60068-2-2. Meets MIL-PRF-28800F Class 3 low temperature limit and MIL-PRF-28800F Class 2 high temperature limit.)
Relative humidity range	10% to 90%, noncondensing (Tested in accordance with IEC 60068-2-56.)

Storage Environment

Ambient temperature range	-40 °C to 71 °C (Tested in accordance with IEC 60068-2-1 and IEC 60068-2-2. Meets MIL-PRF-28800F Class 3 limits.)
Relative humidity range	5% to 95%, noncondensing (Tested in accordance with IEC 60068-2-56.)

Shock and Vibration

Operating shock	30 g peak, half-sine, 11 ms pulse (Tested in accordance with IEC 60068-2-27. Meets MIL-PRF-28800F Class 2 limits.)

Random vibration

Operating	5 Hz to 500 Hz, $0.3~g_{rms}$
Nonoperating	5 Hz to 500 Hz, 2.4 g _{rms} (Tested in accordance with IEC 60068-2-64. Nonoperating test profile exceeds the requirements of MIL-PRF-28800F, Class 3.)

Compliance and Certifications

Safety

This product is designed to meet the requirements of the following electrical equipment safety standards for measurement, control, and laboratory use:

- IEC 61010-1, EN 61010-1
- UL 61010-1, CSA 61010-1



Note For UL and other safety certifications, refer to the product label or the *Online* Product Certification section.

Electromagnetic Compatibility

This product meets the requirements of the following EMC standards for electrical equipment for measurement, control, and laboratory use:

- EN 61326-1 (IEC 61326-1): Class A emissions; Basic immunity
- EN 55011 (CISPR 11): Group 1, Class A emissions
- EN 55022 (CISPR 22): Class A emissions
- EN 55024 (CISPR 24): Immunity
- AS/NZS CISPR 11: Group 1, Class A emissions
- AS/NZS CISPR 22: Class A emissions
- FCC 47 CFR Part 15B: Class A emissions
- ICES-001: Class A emissions



Note In the United States (per FCC 47 CFR), Class A equipment is intended for use in commercial, light-industrial, and heavy-industrial locations. In Europe, Canada, Australia, and New Zealand (per CISPR 11), Class A equipment is intended for use only in heavy-industrial locations.



Note Group 1 equipment (per CISPR 11) is any industrial, scientific, or medical equipment that does not intentionally generate radio frequency energy for the treatment of material or inspection/analysis purposes.



Note For EMC declarations, certifications, and additional information, refer to the Online Product Certification section.

CE Compliance ζ

This product meets the essential requirements of applicable European Directives, as follows:

- 2014/35/EU; Low-Voltage Directive (safety)
- 2014/30/EU; Electromagnetic Compatibility Directive (EMC)

Online Product Certification

Refer to the product Declaration of Conformity (DoC) for additional regulatory compliance information. To obtain product certifications and the DoC for this product, visit *ni.com/certification*, search by model number or product line, and click the appropriate link in the Certification column.

Environmental Management

NI is committed to designing and manufacturing products in an environmentally responsible manner. NI recognizes that eliminating certain hazardous substances from our products is beneficial to the environment and to NI customers.

For additional environmental information, refer to the *Minimize Our Environmental Impact* web page at *ni.com/environment*. This page contains the environmental regulations and directives with which NI complies, as well as other environmental information not included in this document.

Waste Electrical and Electronic Equipment (WEEE)



EU Customers At the end of the product life cycle, all NI products must be disposed of according to local laws and regulations. For more information about how to recycle NI products in your region, visit *ni.com/environment/weee*.

电子信息产品污染控制管理办法(中国 RoHS)

中国客户 National Instruments 符合中国电子信息产品中限制使用某些有害物质指令(RoHS)。关于 National Instruments 中国 RoHS 合规性信息,请登录 ni.com/environment/rohs_china。(For information about China RoHS compliance, go to ni.com/environment/rohs china.)

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